

# LDP24A

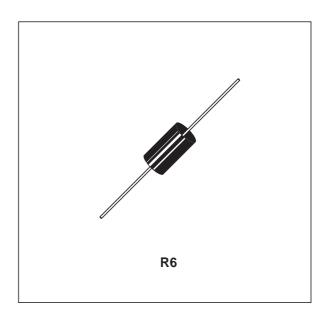
# TRANSIENT PROTECTION LOAD DUMP

#### **FEATURES**

- TRANSIENT VOLTAGE SUPPRESSOR DIODE ESPECIALLY DESIGNED FOR LOAD DUMP PROTECTION
- COMPLIANT WITH MAIN STANDARDS SUCH AS: ISO / DTR 7637

#### **DESCRIPTION**

Transient voltage suppressor diodes especially useful in protecting integrated circuits, MOS, hybrids and other overvoltages sensitive semiconductors and components.



#### **ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter	Value	Unit	
$V_{PP}$	Peak pulse load dump overvoltage See note 1 T <sub>amb</sub> = 85°C		100	V
Р	Power dissipation on infinite heatsink	5	W	
I <sub>FSM</sub>	Non repetitive surge peak forward current. T <sub>j</sub> initial = 25°C tp = 10 ms		500	А
T <sub>stg</sub>	Storage temperature range.		- 65 to + 175	°C
Tj	Maximum operating temperature		175	°C
$T_L$	Maximum lead temperature for soldering during 10 sec at 4 mm from case.		230	°C

#### THERMAL RESISTANCES

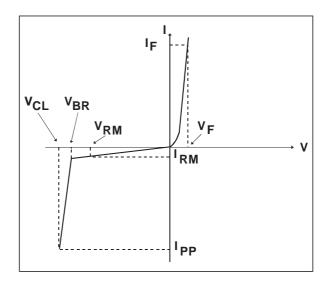
Symbol	Parameter	Value	Unit
R <sub>th</sub> (j-a)	Junction ambient thermal resistance on infinite heatsink L <sub>lead</sub> = 10 mm	15	°C/W

Note 1: For surges greater than the maximum values, the diode will present a short-circuit Anode - Cathode.

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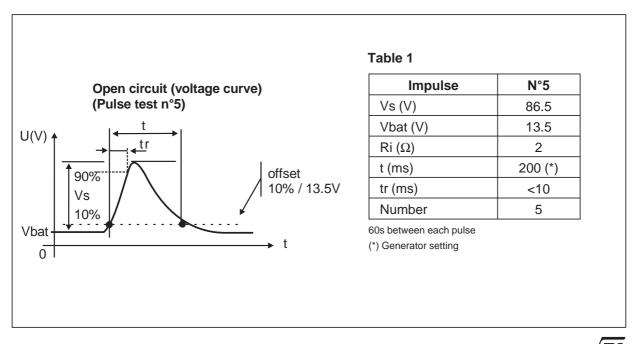
#### **ELECTRICAL CHARACTERISTICS**

Symbol	Parameter				
V <sub>RM</sub>	Stand-off voltage.				
V <sub>BR</sub>	Breakdown voltage.				
V <sub>CL</sub>	Clamping voltage.				
I <sub>PP</sub>	Peak pulse current.				
αт	Temperature coefficient of V <sub>BR</sub> .				
С	Capacitance				
I <sub>RM</sub>	Leakage current at V <sub>RM</sub>				
V <sub>F</sub>	Peak forward voltage drop				



Symbol		Min.	Тур.	Max.	Unit	
lpp	Pulse duration: 4	30			А	
I <sub>RM</sub>	T <sub>j</sub> = 25°C T <sub>j</sub> = 85°C	V <sub>RM</sub> = 24 V V <sub>RM</sub> = 24 V			50 300	μΑ μΑ
$V_{BR}$	T <sub>i</sub> = 25°C	I <sub>R</sub> = 1mA	25		32	V
V <sub>CL</sub>	T <sub>i</sub> = 85°C see table1				40	V
αΤ					10	10 <sup>-4</sup> /°C
С	F = 1MHz	$V_R = 0V$		8000		pF
V <sub>F</sub>	I <sub>FM</sub> = 10A			0.9		V

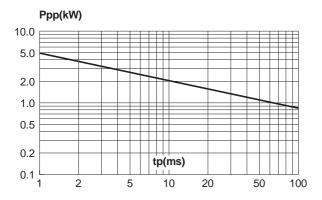
### LOAD DUMP TEST GENERATOR CIRCUIT (SCHAFFNER NSG 506 C). Issued from ISO / DTR 7637.



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Downloaded from Arrow.com.

**Fig. 1:** Peak pulse power versus exponential pulse duration (Tj initial=85°C).



**Fig. 3:** Relative variation of peak pulse power versus junction temperature.

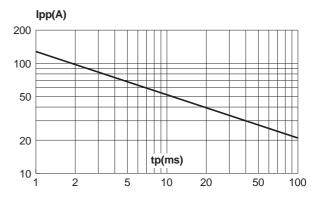


Fig. 2: Peak pulse current versus exponential

pulse duration (Tj initial=85°C).

**Fig. 4:** Continous power dissipation versus ambient temperature.

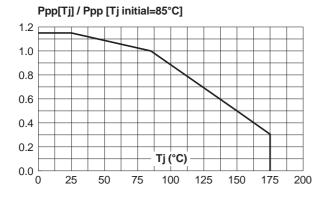
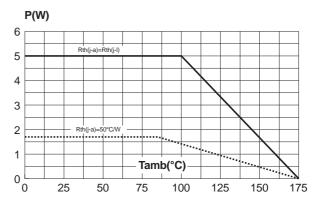
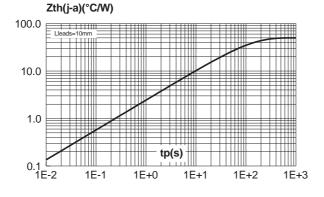
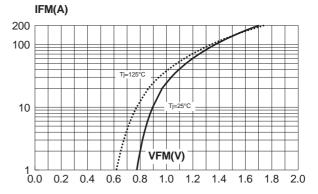


Fig. 5: Variation of thermal impedance junction to ambient versus pulse duration (printed circuit board FR4,  $e(Cu)=35\mu m$ ,  $SCu=1cm^2$ ).



**Fig. 6 :** Peak forward voltage drop versus peak forward current (typical values).



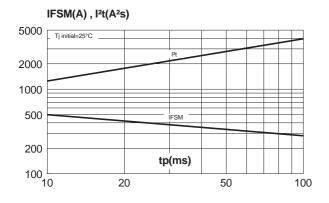


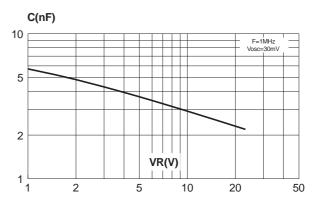
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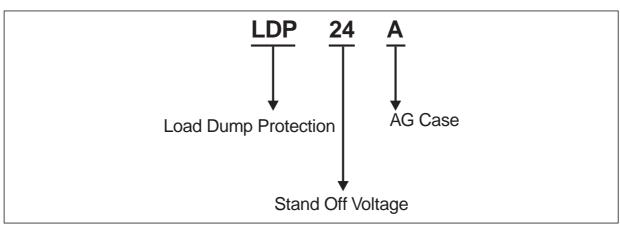
Fig. 7: Non repetitive surge peak forward current versus sinusoidal pulse duration and corresponding value of  $\rm I^2 t$ .

**Fig. 8:** Junction capacitance versus reverse applied voltage.





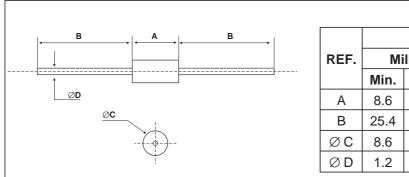
#### **ORDER CODE**



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#### **PACKAGE MECHANICAL DATA**

R6 (Plastic)



	DIMENSIONS						
REF.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	8.6		9.1	0.338		0.358	
В	25.4			1			
ØC	8.6		9.1	0.338		0.358	
ØD	1.2		1.3	0.047		0.051	

Туре	Marking	Package	Weight	Base qty	Delivery mode
LDP24A	LDP24A	R6	2.048 g	100	Ammopack
LDP24ARL	LDP24A	R6	2.048 g	1000	Tape & Reel

Resin meets UL94-V0

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